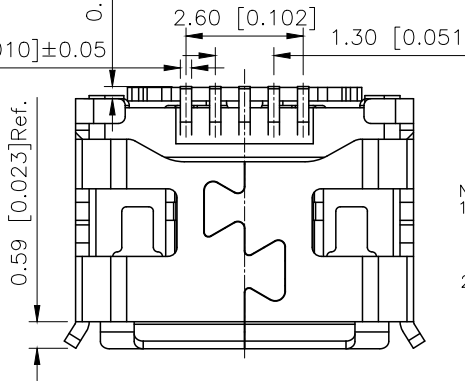
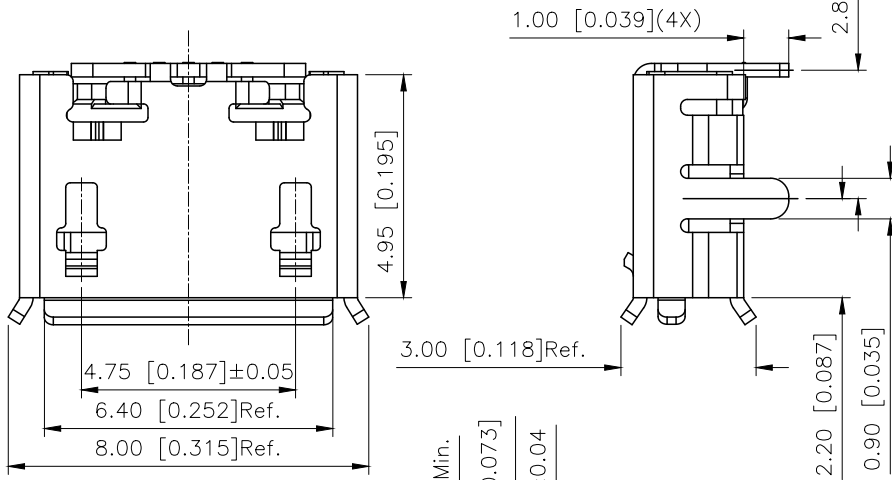
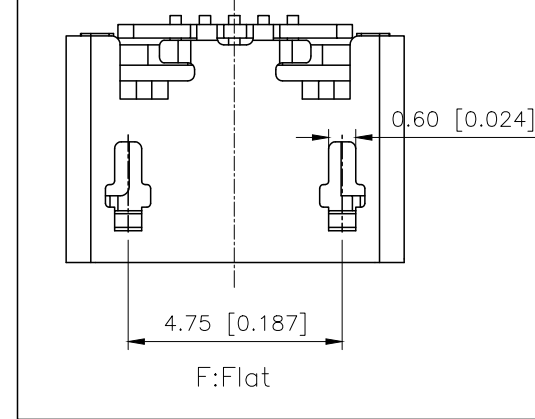
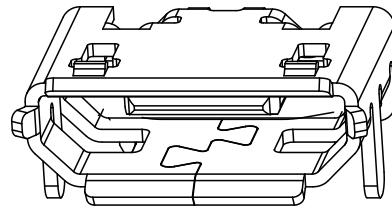
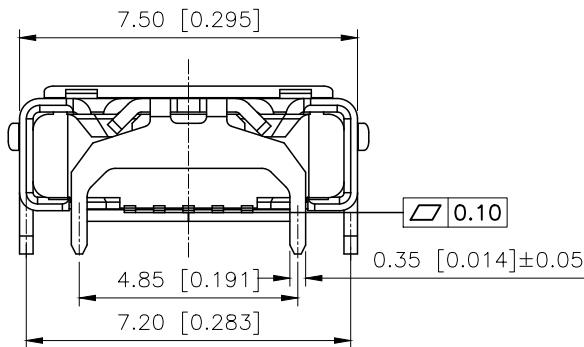
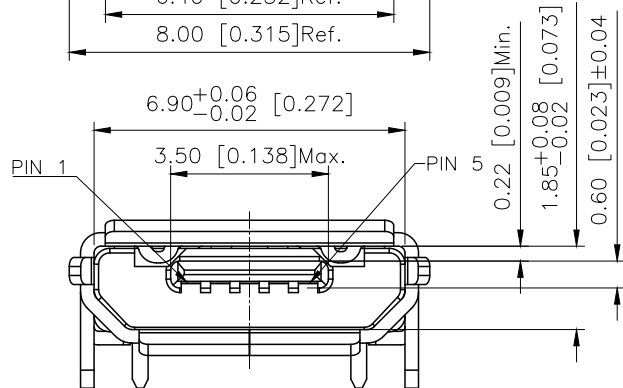


REVISIONS					
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A0	N/A		INITIAL RELEASE	/	/
A1	N/A		图面升级整理图面	2025.03.05	阿树



NOTE:
1.MATERIAL SPECIFICATION:
1.HOUSING:LCP,UL94 V-0 BLACK.
2.CONTACTS: BRASS(C2680 T=0.15)
3.FRONT SHELL: STAINLESS STEEL(SUS304 T=0.3)
2.PLATING SPECIFICATION:
2-1.CONTACTS:
Ni 50u" MIN. UNDER PLATED OVER ALL.
Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.
(GOLD PLATING THICKNESS FOLLOW THE P/N)
PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N
2-2.FRONT SHELL:
SEE TABLE 1.
50u" MIN. NICKEL UNDER PLATING OVER ALL.
3.MECHANICAL PERFORMANCE,
3-1.INSERTION FORCE: 3.5kgf MAX
3-2.REMOVAL FORCE: 0.8kgf MIN
3-3.DURABILITY: 10000 CYCLES.
4.ELECTRICAL PERFORMANCE,
4-1.CURRENT RATING:
VBUS & GND PINS: 1.8A MAX.
OTHER PINS: 0.5A MAX.
4-2. LLCR:
VBUS & GND PINS AND OTHER PINS: 30mΩ/PIN MAX.
SHIELD: 50mΩ/MAX.
LLCR MAX. CHANGE OF ALL PINS: 10mΩ.
4-3.INSULATION RESISTANCE: 100MΩ MIN
4-4.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.
5. ENVIRONMENTAL PERFORMANCE:
OPERATING TEMPERATURE: -25°C~+85°C.
6.IR REFLOW:
THE PEAK TEMPERATURE ON THE BOARD SHALL
BE MAINTAINED FOR 10 SECONDS AT 260°C.



U254-05XX-4BH23-X2S

1:AU 1U"
6:AU 30U"
T:TIN
N:NICKEL

S:Sus
2:WITHOUT
S:Scrolls F:Flat

AuGLAR	±5°
X.	±0.40
X.x	±0.30
X.xx	±0.20
X.xxx	±0.15
UNSPECIFIED TOLERANCES	



DESIGN	阿树	VIEW:		MODEL TYPE:	MICRO USB
CHECKED		UNIT:	mm/in	PART NO.:	U254-05XX-4BH23-X2S
APPROVED		SIZE:	A4	DWG NO.:	